

## Technical Data Sheet

### ASSEMBLY MATERIALS

**Product Type:** No Clean Solder Paste

**Product Name:** FC712 SAC305-88P4

#### Description

FC712 SAC305-88P4 solder paste is a state-of-the-art lead free no clean solder paste that promotes outstanding wetting and minimizes soldering defects. The FC712 flux system is specifically optimized for lead free alloys, e.g. Sn/Ag/Cu. This formula provides superior performance on a variety of surfaces finishes and leaves behind a clear residue.

#### Key Benefits

- Stable viscosity for long stencil life
- Good soldering performance in air reflow
- Good fine pitch printing performance

#### Applications

- Printing

#### Product Code and Alloy

Product Code					Powder Properties		
Paste	Alloy	Metal Content	*Viscosity	Powder Type	Particle Size	Alloy	Melting Point
FC712	SAC305	88%	P	4	20 – 38 µm	Sn96.5/Ag3/Cu0.5	217 °C

\*D = Dispense grade P = Print grade L = Dipping/Jetting grade, Low

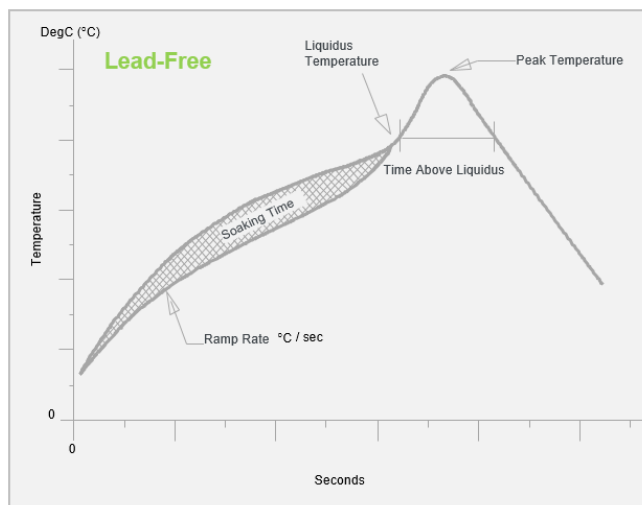
#### Flux Activity

Activity Level (J-STD 004)	Classification
ROLO	No Clean/ Solvent Clean

#### Halogen Content

Halogen-Zero (No halogen added in the flux)
Tolerances: Halogen < 50 ppm; measured according to BS EN 14582

#### Recommended Reflow Profile



\* Graph not drawn to scale

#### Recommended Profile

<b>Average Ramp Rate</b>	<b>1 – 3 °C/s</b>
<b>Peak Temperature</b>	<b>15 °C (min) – 40 °C (max) above Melting Temperature</b>
<b>Time above liquidus</b>	<b>45 – 90 s</b>
<b>Reflow Atmosphere</b>	<b>Reflow in Air or in N<sub>2</sub> with &lt; 2000 ppm O<sub>2</sub></b>
<b>Type 3 – 5</b>	

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### Cleaning Instructions

After reflow flux residues may remain on the circuit and do not need to be washed. For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used – see separate cleaning recommendations.

### Storage

- Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 - 10 °C

### Paste Preparation

- Remove paste from fridge: Before opening the package, leave paste for at least 4 hours (depending on jar/ cartridge size) at room temperature, so that paste warms up
- Do not open jar/cartridge while paste is cold to prevent condensation
- Do not heat the paste beyond room temperature

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